

10/075566  
02/13/02

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PATENT NUMBER and  
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10075566	FILING DATE 02/13/2002	CLASS 134	SUBCLASS 003	GAU 1746	EXAMINER CHAUDHRY
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\*\*APPLICANTS: Aoki Hidemitsu; Yamasaki Shinya;

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\*\*CONTINUING DATA VERIFIED:

THIS APPLICATION IS A DIV OF 09/313,027 05/17/1999

\*\* FOREIGN APPLICATIONS VERIFIED:

JAPAN 10-138365 05/20/1998

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiner's initials		<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO 12688A
TITLE : Method for cleaning semiconductor wafer after chemical mechanical polishing on copper wiring U.S. DEPT. OF COMM./PAT. & TM-PTO-436L(Rev. 12-94)			

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G
ISSUE FEE		DRAWING		
Amount Due	Date Paid	Sheets Drwg.	Figs.Drwg.	Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Primary Examiner		
		Application Examiner		
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